rev 2.0 07.06.2016

# LED545-01

• Green LED

• 545 nm, 2 mW

• Chip Material: InGaN

• 5 mm Clear Mold, Epoxy Resin

• Viewing Angle: 16°





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### Description

**LED545-01** contains a InGaN LED mounted on a lead frame hermetically sealed with a clear epoxy lens. On forward bias, it emits a power radiation of typical **2 mW** at a peak wavelength at **545 nm**.

### Maximum Ratings (TCASE=25°C)

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Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	$P_D$		180	mW	
Forward Current	I <sub>F</sub>		50	mA	
Pulse Forward Current *1	<b>I</b> FP		100	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	R <sub>THJA</sub>		330	K/W	
Junction Temperature	$T_J$		100	°C	
Operating Temperature	$T_{CASE}$	- 40	+ 85	°C	
Storage Temperature	T <sub>STG</sub>	- 40	+ 100	°C	
Lead Solder Temperature *2	$T_{SLD}$		+ 265	°C	

<sup>\*1</sup> duty=1%, pulse width = 10  $\mu$ s

## Electro-Optical Characteristics (TCASE=25°C)

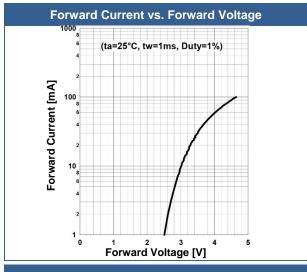
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	$\lambda_P$	I <sub>F</sub> =20mA	535	545	555	nm
Half Width	$\Delta \lambda$	I <sub>F</sub> =20mA		36		nm
Dominant Wavelength	$\lambda_D$	I <sub>F</sub> =20mA				
Forward Voltage	VF	I <sub>F</sub> =20mA		3.2		V
Radiated Power *1	Po	I <sub>F</sub> =20mA		2		mW
Radiant Intensity *2	ΙE	I <sub>F</sub> =20mA		9.3		mW/sr
Brigthness	Iv	I <sub>F</sub> =20mA		7		cd
Viewing Angle	φ	I <sub>F</sub> =20mA		16		deg.

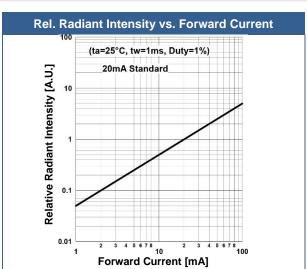
<sup>\*1</sup> measured by S3584-08

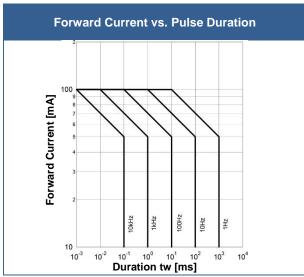
<sup>\*2</sup> must be completed within 3 seconds

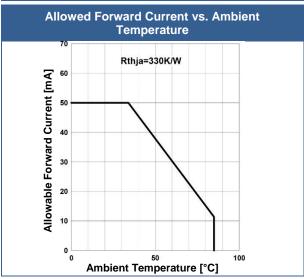
<sup>\*2</sup> measured by Tektronix J-6512

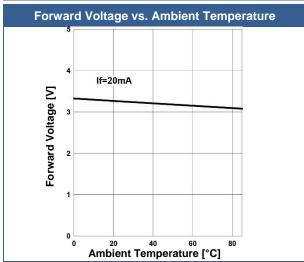
## **Typical Performance Curves**

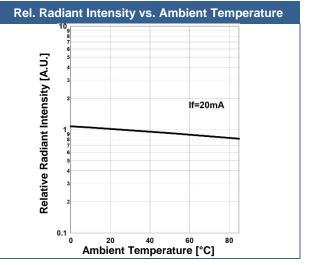










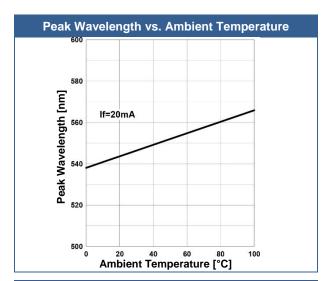


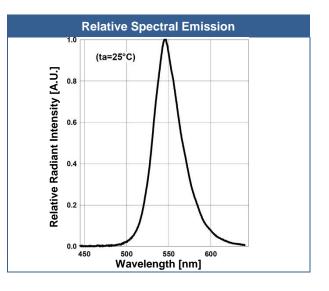


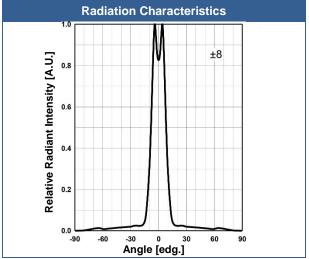
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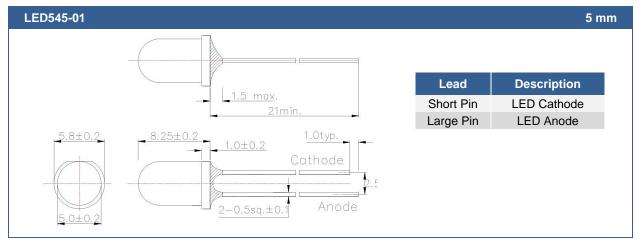








### **Outline Dimensions**



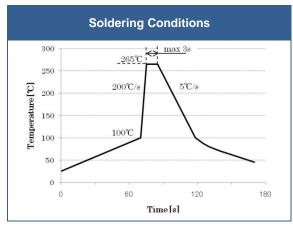
All Dimensions in mm

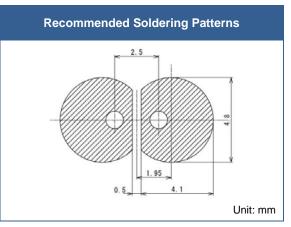
#### **Precautions**

#### Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering
- Do not solder the LED closer than 3 mm from the base of the lead.

#### Recommended soldering conditions:





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

#### Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

#### **Static Electricity:**

**LEDs are sensitive to electrostatic discharge (ESD)**. Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

#### Radiation:

During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. Protective glasses if needed. It is further advised to attach a warning label on products/systems.

#### Operation:

#### Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

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